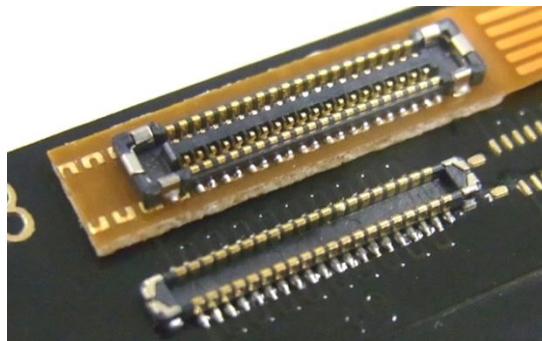


## BM23(0.6) Series

### 0.35mm Pitch, 0.6mm Stacking Height, FPC to Board Connectors



#### ◆Features

1. Space saving: 0.35mm pitch, 0.6mm stacking height, 1.98mm depth
2. Robust structure with metal fittings
3. Large vacuum pick & place area configured in space with 1.98mm depth
4. Clear tactile click
5. Highly reliable 2-point contact and retention force with clipping contact design
6. Increased self-alignment range with metal guide implemented in open space
7. Supports USB 3.1 gen.2 (10Gbps) transmission
8. Solder wicking prevention
9. Contact protection against dust

#### ◆Specifications

##### • Material and Finish

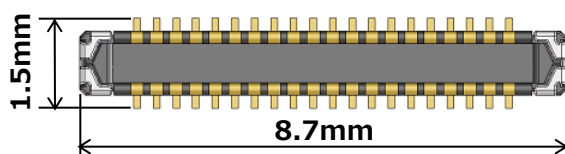
COMPONENT	MATERIAL	FINISH
Housing	LCP	Black, UL94V-0
Contact	Phosphor bronze	Gold plated over Nickel under plating
Metal Fitting	Phosphor bronze	Gold plated over Nickel under plating

##### • Performance Characteristics

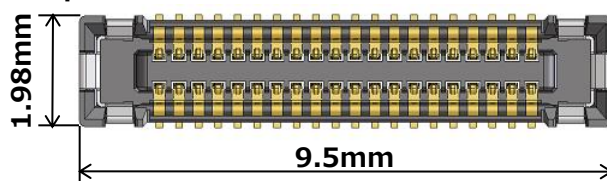
Rated Current	0.3A
Rated Voltage	30V AC/DC
Operating Temperature	-55°C to +85°C (Include the temperature rising by current flow)
Contact Resistance	100mΩ Max. (20mV AC or 1000Hz)
Withstanding Voltage	100V AC for 1 minute
Insulation Resistance	50MΩ or above (100V DC)
Durability	10 cycles

#### ◆Dimensions (40pos.)

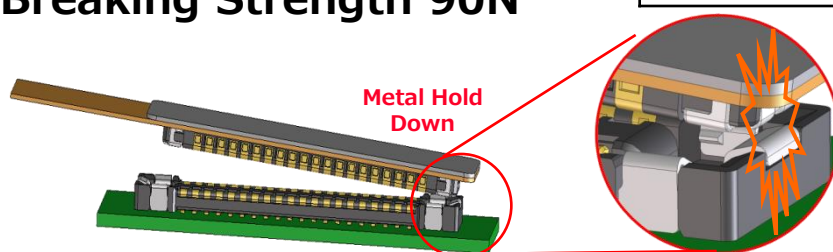
##### • Header



##### • Receptacle



#### ◆Robust Structure: Breaking Strength 90N



If the header and the receptacle should be mated offset incorrectly, the metal hold down would ease the impact and prevent the housing from cracking and breaking.

Specifications herein are subject to change without notice. Contact Hirose for the latest specifications, drawings, and availabilities.